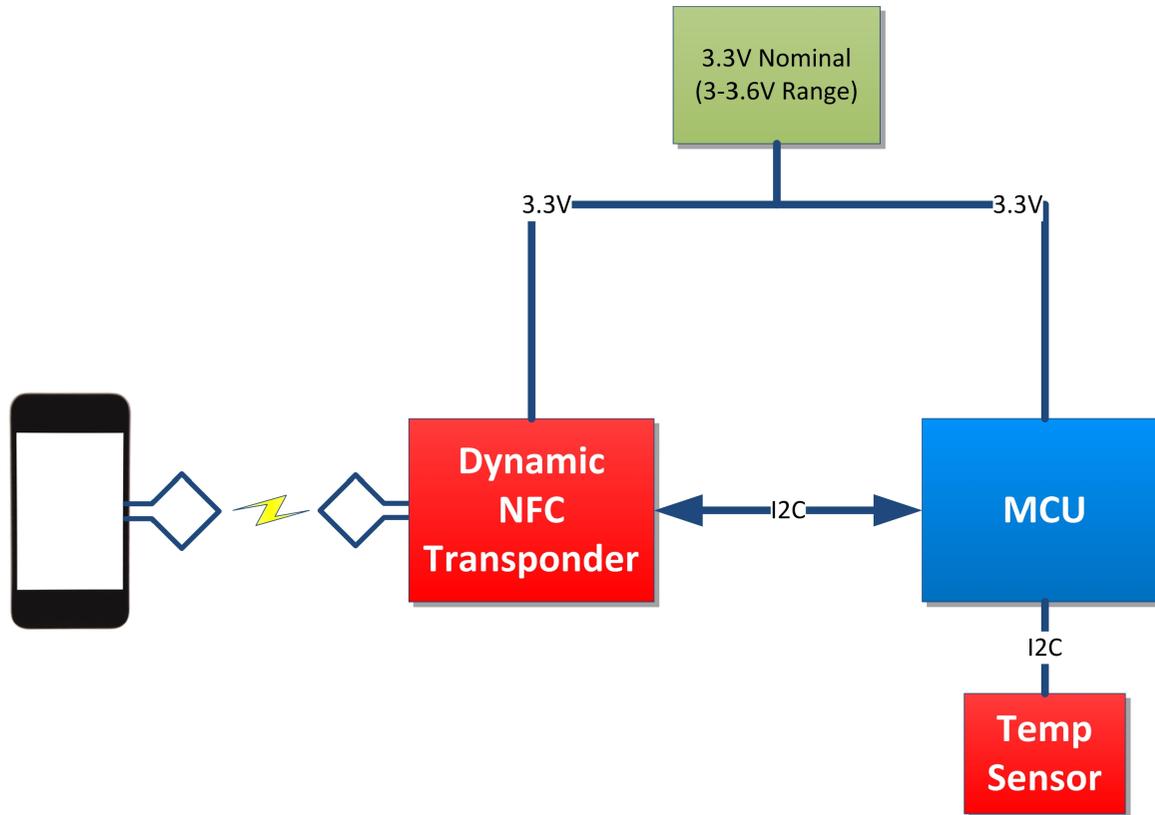


# TIDA-00217

## Field Powered NFC and Microcontroller Reference Design

Revision History	
Revision	Notes

### System Block Diagram

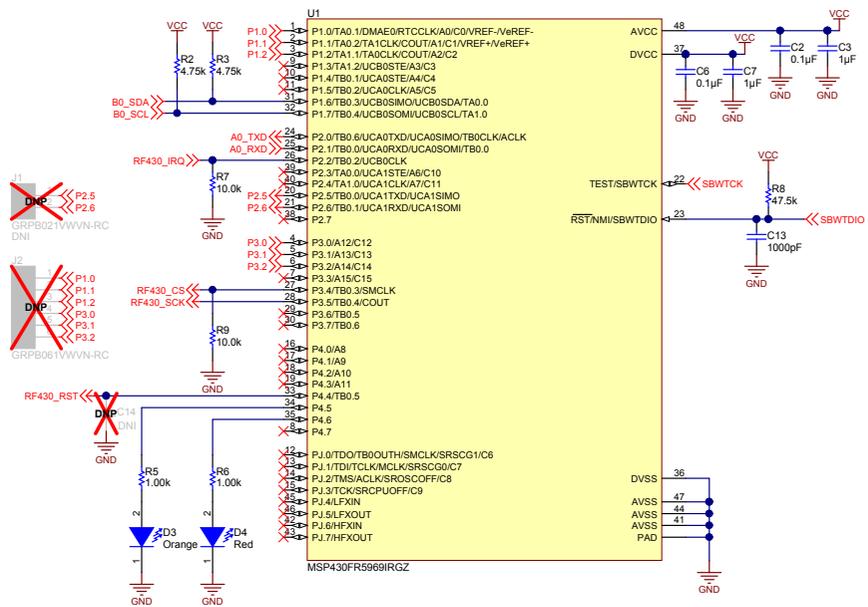


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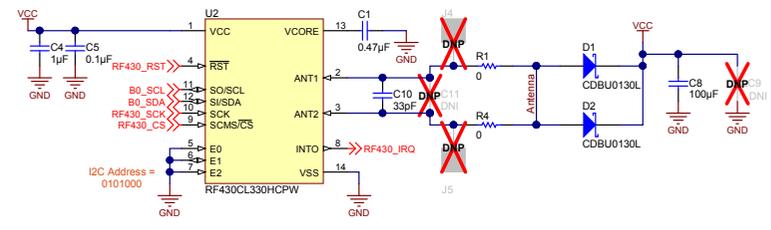
Designed for: Public Release		Mod. Date: 6/11/2014	
Project Title: NFC Authentication			
Number: ISE4003	Rev: E2	Sheet Title:	
SVN Rev: Not in version control		Assembly Variant: 001	Sheet: 1 of 3
Drawn By:	File: ISE4003 Cover Sheet SchDoc	Size: B	
Engineer: Evan Cornell	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	<a href="http://www.ti.com">http://www.ti.com</a>	
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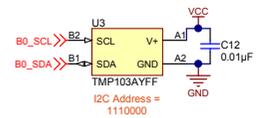
### MSP430 Microcontroller



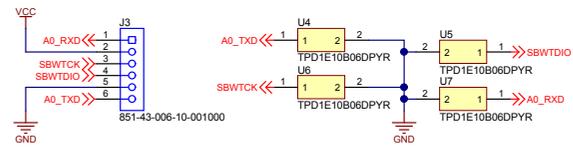
### RF430 Dynamic NFC Transponder



### Local Temperature Sensor



### SBW Interface & ESD Protection



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Designed for: Public Release		Mod. Date: 6/11/2014	
Project Title: NFC Authentication			
Sheet Title:			
Number: ISE4003		Rev: E2	
SVN Rev: Not in version control		Assembly Variant: 001	
Drawn By:		File: ISE4003 Sheet 1.SchDoc	
Engineer: Evan Cornell		Contact: http://www.ti.com/support	
Sheet: 2 of 3		Size: B	
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PCB Number: ISE4003  
PCB Rev: E2

PCB  
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You should delete the nylon screws/standoffs and/or the bump-ons as needed for your design (or substitute other parts from Hardware.IntLib). Bump-ons are cheaper, but provide less clearance.

Deleting anything else from this page may result in your EVM submission being rejected (until you add them back).

Update the Label Text in the Label Table as needed for each Assembly Variant.

You can delete this note too.

Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

ZZ1  
**Label Assembly Note**  
This Assembly Note is for PCB labels only

ZZ2  
**Assembly Note**  
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3  
**Assembly Note**  
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4  
**Assembly Note**  
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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Designed for: Public Release		Mod. Date: 6/11/2014	
Project Title: NFC Authentication		Sheet Title:	
Number: ISE4003	Rev: E2	Assembly Variant: 001	Sheet: 3 of 3
SVN Rev: Not in version control	Drawn By:	File: Hardware_ANSI-B_SchDoc	Size: B
Engineer: Evan Cornell	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	 <a href="http://www.ti.com">http://www.ti.com</a> <small>© Texas Instruments 2014</small>	

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